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1-31-92

4-30-01



U.S. DEPARTMENT OF COMM.  
Patent and Trademark

Docket No.: 50212-223

101731317

To the Honorable Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of Conveying Party(ies):  
Yuichi WADA, Hiroyuki YARITA, Hisashi AIDA, and  
Naomi YOSHIDA

2. Name and address of receiving party(ies):  
Name: APPLIED MATERIALS INC.  
  
Address: 3050 Bowers Avenue  
  
Santa Clara, California 95054

Additional name(s) of conveying party(ies) attached?  Yes

3. Nature of Conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other

Execution Date: Apr. 26, Apr. 25, Apr. 25, and Apr. 25, 2001  
(respectively)

Additional name(s) & address(es) attached?  Yes

4. Application number(s) or patent number(s):  
If the document is being filed together with a new application, the execution date of the application is: Apr. 26, Apr. 25, Apr. 25,  
and Apr. 25, 2001  
(respectively)

A. Patent Application No(s).

05/03/2001 SNAJARRD 00000030 500417 09830803  
02 FD:581 10.00 CH

B. Patent No(s).

09/830803

Additional numbers attached?  Yes

5. Name and address of party to whom correspondence  
concerning document should be mailed:

Name: MCDERMOTT, WILL & EMERY

Internal Address:

Street Address: 600 13<sup>th</sup> Street, N.W.

City: Washington State: DC Zip: 20005

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number:

500417

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy  
of the original document.*

Arthur J. Steiner, 26,106

April 30, 2001

Name and Registration No. of Person Signing

Signature

Date

Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

PATENT  
REEL: 011831 FRAME: 0892

# ASSIGNMENT

Whereas, I/we,

Name

Address

1) **Yuichi WADA**

c/o Applied Materials Japan, Inc.,  
14-3, Shinizumi,  
Narita-shi, Chiba 286-8516 Japan  
c/o Applied Materials Japan, Inc.,

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c/o Applied Materials Japan, Inc.,

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4) **Naomi YOSHIDA**

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Narita-shi, Chiba 286-8516 Japan

hereinafter called assignor(s), have invented certain improvements in  
**FILM DEPOSITION METHOD AND APPARATUS FOR SEMICONDUCTOR DEVICES**

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on \_\_\_\_\_, Serial No. \_\_\_\_\_; and

Whereas

**APPLIED MATERIALS INC.**

3050 Bowers Avenue,  
Santa Clara, California 95054 United States of America

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

INVENTORS

DATE SIGNED

1):

Name:

Yuichi Wada  
Yuichi WADA

4/26/01

2):

Name:

Hiroyuki Yarita  
Hiroyuki YARITA

4/25/01

3):

Name:

Hisashi Aida  
Hisashi AIDA

4/26/01

4):

Name:

Naomi YOSHIDA

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. § 261)

For Non-U.S. Clients

# ASSIGNMENT

Whereas, I/we,  
Name

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- 1) Yulohi WADA  
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- 4) Naomi YOSHIDA  
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<u>INVENTORS</u>	<u>DATE SIGNED</u>
1): Name: <u>Yulohi WADA</u>	
2): Name: <u>Hiroyuki YARITA</u>	
3): Name: <u>Hieashi AJDA</u>	
4): Name: <u>Naomi YOSHIDA</u>	<u>4/25/01</u>

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